

P-Channel Silicon MOSFET

General Description

The IRF5803B uses advanced trench technology and design to provide excellent RDS(ON). This device is ideal for battery and load management applications.

Features

- P-Channel
- Low ON-resistance
- Surface Mount
- RoHS Compliant

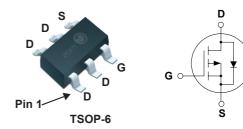
Product Summary

BVDSS	RDSON	ID
-60V	98mΩ	-4.0A

Applications

- Inverters
- Power Supplies
- DC / DC converter

TSOP-6 Pin Configuration



Type	Package	Marking
IRF5803B	TSOP-6	3GNRB

Absolute Maximum Ratings

Symbol	Parameter Rating		Units	
V_{DS}	Drain-Source Voltage	-60	V	
V_{GS}	Gate-Source Voltage ±20			
I _D @T _A =25℃	Continuous Drain Current -4		Α	
I _{DM}	Pulsed Drain Current	-16	Α	
P _D @T _A =25℃	Total Power Dissipation ¹	2	W	
T _{STG}	Storage Temperature Range -55 to 150		$^{\circ}$	
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}$ C	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹		62.5	°C/W



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Electrical Characteristics (T_J =25 $^{\circ}$ C , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-60			V
D	Static Drain-Source On-Resistance	V _{GS} =-10V, I _D =-3.5A			98	mΩ
R _{DS(ON)}		V_{GS} =-4.5V, I_{D} =-2.5A			110	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250uA$	-1		-3	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-48V , V _{GS} =0V			-1	uA
I _{GSS}	Gate-Source Leakage Current	$V_{GS} = \pm 20V$, $V_{DS} = 0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =-10V , I _D =-2A		3		S
Qg	Total Gate Charge	I _D =-3A		15		
Q _{gs}	Gate-Source Charge	V _{DS} =-24V		2.5		nC
Q_{gd}	Gate-Drain Charge	V _{GS} =-10V		3.2		
T _{d(on)}	Turn-On Delay Time	V _{DD} =-24V		11		
T _r	Rise Time	I _D =-1.5A		13		
T _{d(off)}	Turn-Off Delay Time	R _L =16Ω		55		ns
T _f	Fall Time	V _{GS} =-10V		28		
C _{iss}	Input Capacitance			1600		
Coss	Output Capacitance	V _{DS} =-20V, V _{GS} =0V , f=1MHz		75		pF
C _{rss}	Reverse Transfer Capacitance			50		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
trr	Reverse Recovery Time	I _F =-2A		25		ns
Qrr	Reverse Recovery Charge	dl/dt=-100A/µs		34		nC
V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =-2A			-1.2	V

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^{1.}Surface mounted on 1 in square Cu board